<Reference Photos>

Photo 1: 35 um-pitch lead free bumps formed on detection signal-processing CMOS device

Photo 2: Cross section of interconnect area for chip-on-chip that employs high-precision flip-chip bonding technology to package detection signal-processing CMOS device with X-ray detection device

Photo 3: Exterior view of X-ray image sensor in VATECH's X-ray imaging system using this technology

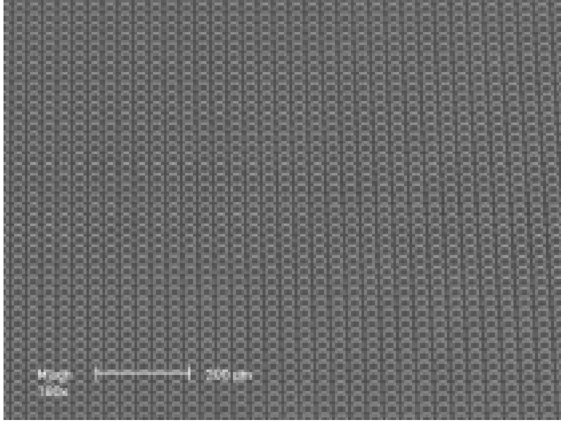
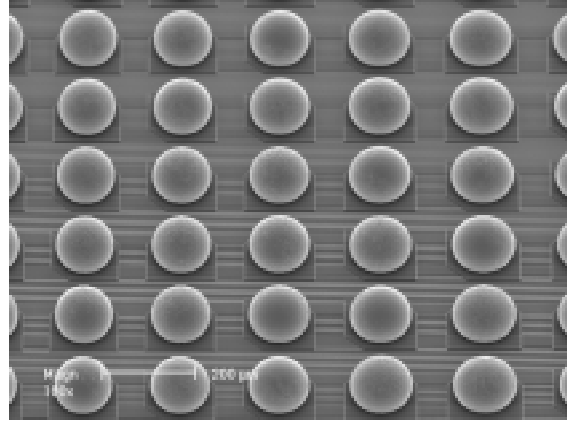


Photo 1: 35 μm-pitch bumps



Reference: 220 μm-pitch bumps

Photo 2: 35 μm-pitch bumps mounting cross section

Reference: 220 μm-pitch bumps mounting cross section

Photo 3: X-ray imaging sensor

Reference: Chip-on-Chip MCM (Upper portion: X-ray detection device, Lower portion: 4 units of detection signal-processing)